

1 ABSTRACT OF THE INVENTION

2 The present invention relates to enhanced protection of the active surface and the
3 bond wires or ball array of a microelectronic device, and to thermal management of the
4 microelectronic device as it is package with a printed circuit board (PCB) or other substrate.
5 The enhanced protection and thermal management are accomplished with a high-temperature
6 thermal grease that is glob topped or encapsulated over the bond wires or ball array, and the
7 active surface of the microelectronic device. The high-temperature thermal grease exchanges
8 heat, particularly by conduction, away from the active surface of the microelectronic device
9 as well as away from the bond wires.

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